APK3216MGC MEGA GREEN

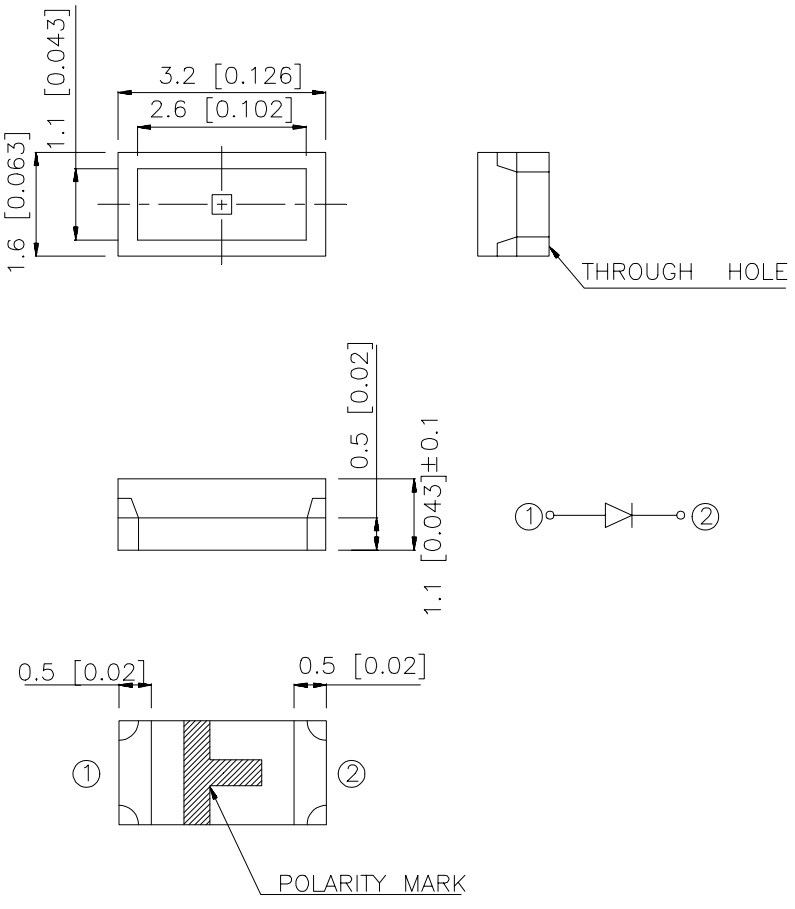
Features

- 3.2mmX1.6mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE :2000PCS / REEL.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.0079") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
APK3216MGC	MEGA GREEN (InGaAlP)	WATER CLEAR	50	120	90°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

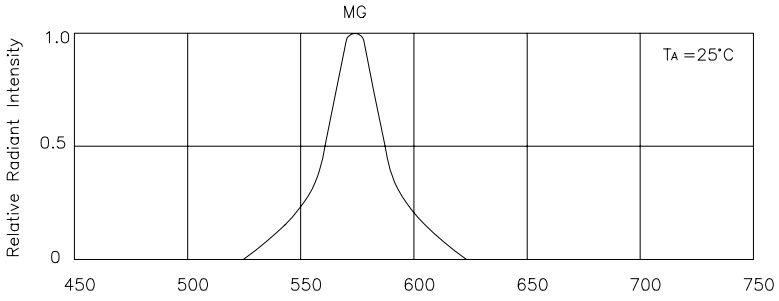
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	I_F=20mA
λ D	Dominate Wavelength	Mega Green	568		nm	I_F=20mA
Δλ 1/2	Spectral Line Half-width	Mega Green	26		nm	I_F=20mA
C	Capacitance	Mega Green	20		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Mega Green	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Mega Green		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

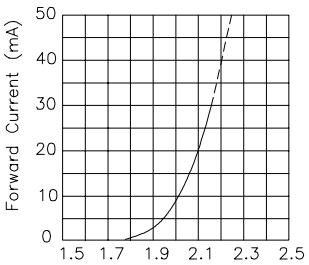
Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

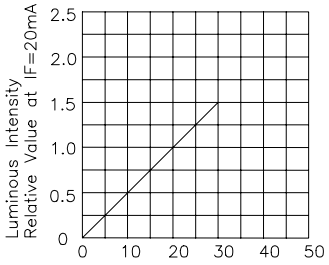


RELATIVE INTENSITY Vs. WAVELENGTH

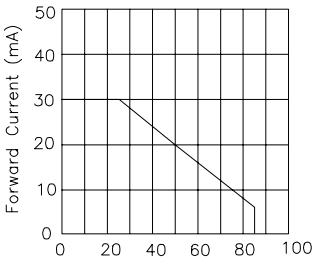
Mega Green APK3216MGC



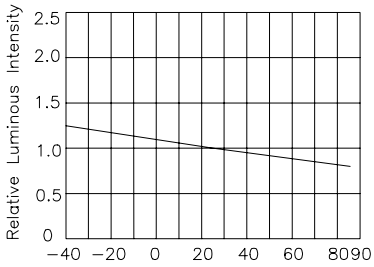
FORWARD CURRENT Vs. FORWARD VOLTAGE



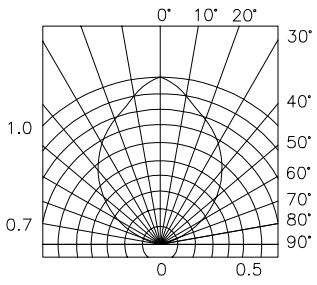
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

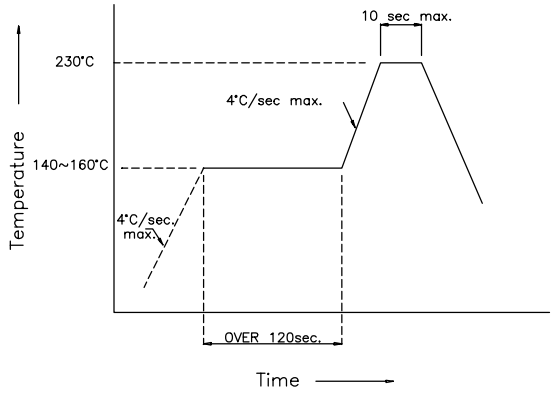


SPATIAL DISTRIBUTION

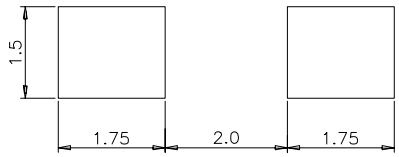
APK3216MGC

SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

